MPI Corporation
6223.TT

Presentation Disclaimer

The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions. All financial figures discussed herein are prepared pursuant to IFRS. All audited figures will be publicly announced upon the completion of our audited process.

MPI Divisions

Since 1995 — Probe Card
Since 2001 — Photonics Automation
Since 2014 — Advanced Semiconductor Test
Since 2015 — Thermal Test
Since 2021 — Celadon Systems

MPI Global Presence

MPI SUZHOU
MPI CELADON
MPI AMERICA
MPI CORPORATION

MPI Offices
MPI Representatives

MPI Locations

Worldwide — Taiwan

MPI America — CA, USA (2017)
MPI Suzhou — Jiangsu, CN (2017)
Celadon Systems — MN, USA (2021)
Headquarters — Hsinchu, TW (2000)
Luzhu Office — Kaohsiung, TW (2006)
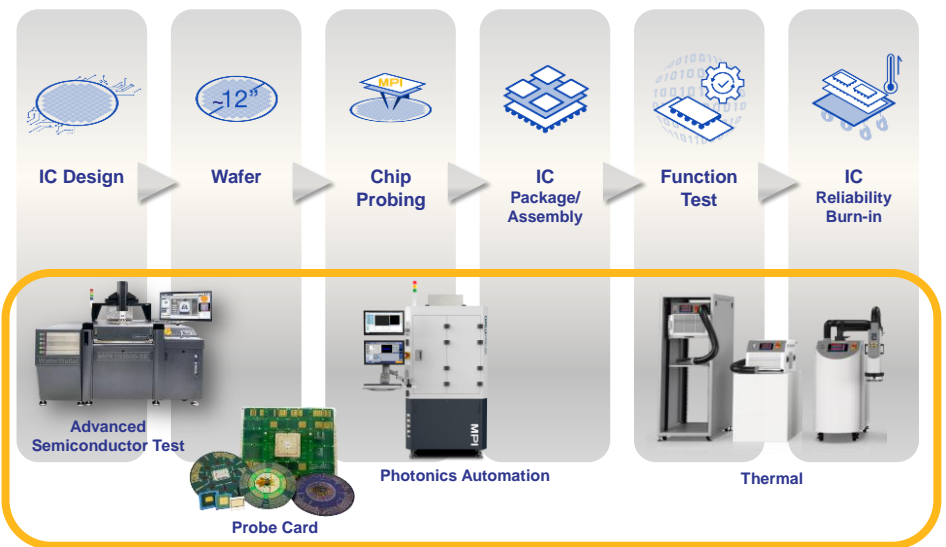2nd Production Site — Hsinchu, TW (2012)
Xinpu Office — Hsinchu, TW (2014)
3rd Production Site — Hsinchu, TW (2021)

MPI-The Powerhouse of Testing Solutions

IC Design	Wafer	Chip Probing	IC Package/ Assembly	Function Test	IC Reliability Burn-in

Advanced Semiconductor Test

Probe Card

Photonics Automation

Thermal

Agenda

Business Contents

Probe Card

Photonics Automation

Thermal & AST

Financial Statements

MPICORPORATION

Probe Card

READY FOR THE TEST™

MPI *Probe Card*
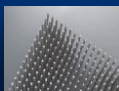
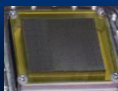Advanced Wafer Sort Test Solutions
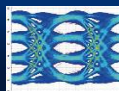
Vertical / MEMS

Cantilever

Features

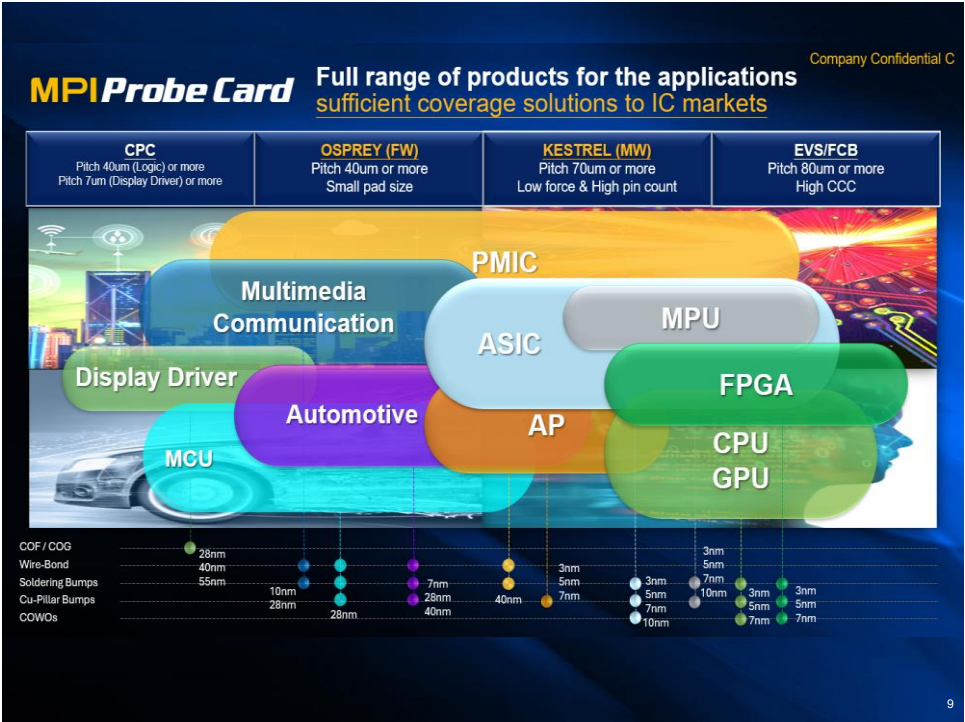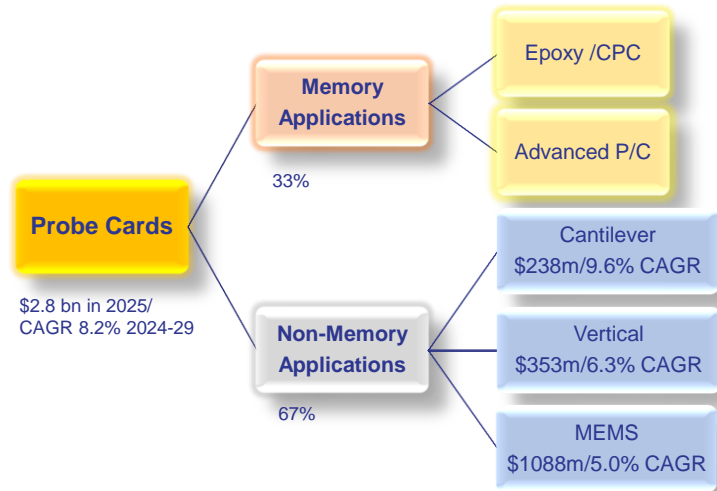| Fine Pitch | MEMS | High Pin Count | High Speed | Substrate | Hand-wired | RF |

Slide 9

MPI Probe Card — **Full range of products for the applications**
sufficient coverage solutions to IC markets

CPC	OSPREY (FW)	KESTREL (MW)	EVS/FCB
Pitch 40um (Logic) or more / Pitch 7um (Display Driver) or more	Pitch 40um or more / Small pad size	Pitch 70um or more / Low force & High pin count	Pitch 80um or more / High CCC

PMIC
Multimedia Communication
MPU
Display Driver
ASIC
FPGA
Automotive
AP
CPU GPU
MCU

COF / COG	28nm						3nm		
Wire-Bond	40nm						5nm		
Soldering Bumps	55nm		7nm		3nm	3nm	7nm	3nm	3nm
Cu-Pillar Bumps		10nm	28nm	40nm	5nm	5nm	10nm	5nm	5nm
COWOs		28nm	40nm		7nm	7nm		7nm	7nm
		28nm				10nm			

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Global Probe Card Market Update

Probe Cards
$2.8 bn in 2025/
CAGR 8.2% 2024-29

Memory Applications
33%
- Epoxy /CPC
- Advanced P/C

Non-Memory Applications
67%
- Cantilever $238m/9.6% CAGR
- Vertical $353m/6.3% CAGR
- MEMS $1088m/5.0% CAGR

Source: TechInsights

Total Own Make IC Probe Cards Venders

(Rank)		2020	2021	2022	2023	2024
FormFactor	USA	1	1	1	1	1
Technoprobe	Italy	2	2	2	2	2
Micronics Japan	Japan	3	3	3	3	3
MPI Corporation	Taiwan	5	5	5	4	4
Japan Electronic Materials	Japan	4	4	4	5	5

Top 10 Probe Cards Revenue ($M)
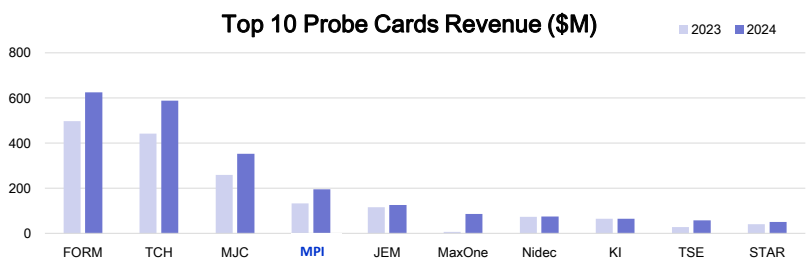
Source: TechInsights

Top 5 Non-Memory Probe Card Vendors

(Rank)		2020	2021	2022	2023	2024
Technoprobe	Italy	2	1	1	1	1
FormFactor	USA	1	2	2	2	2
MPI Corporation	Taiwan	3	3	3	3	3
Nidec SV Probe	Singapore	4	5	4	4	4
Japan Electronic Materials	Japan	5	4	5	5	5

Top 5 Non-Memory Suppliers
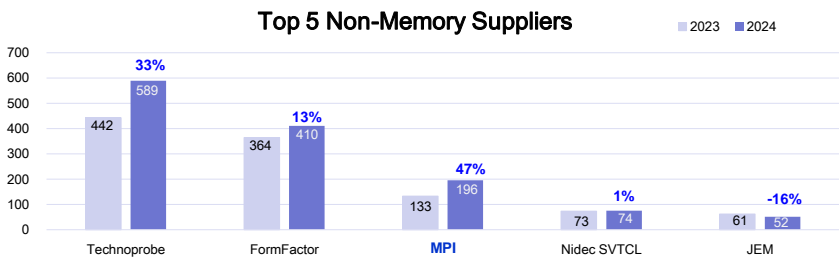
Source: TechInsights

Probe Card: Total Solution Provider

- **Comprehensive Product Range for Circuit Testing**
  全方位的產品布局

  MPI provides omnidirectional products to global customers, including fine pitch CPC, high speed VPC and low force MEMS solutions.
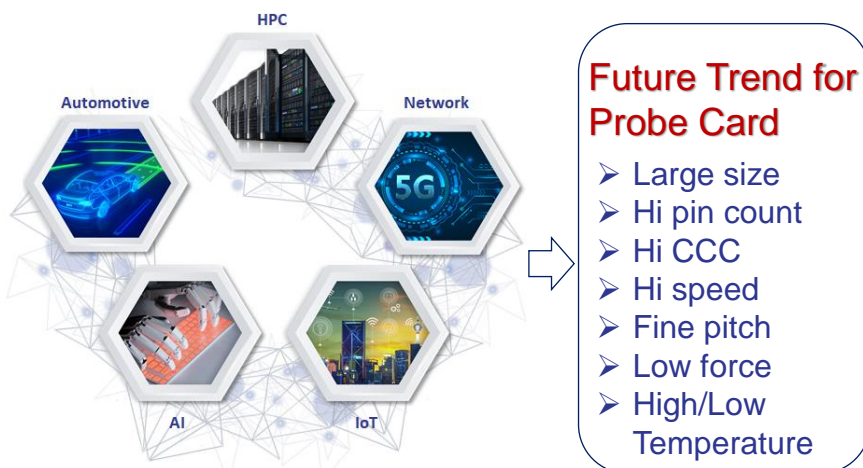
- **Solid Global Clientele 堅實的國際合作夥伴**

  MPI works closely with worldwide market leaders, especially for the AI, HPC application related.

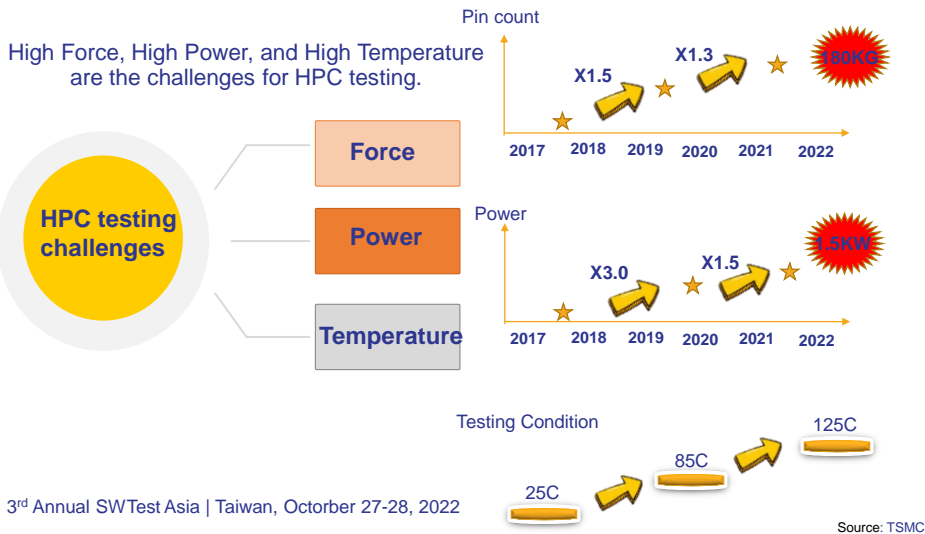- **Complete Probe Card Solution 完整的探針卡整合方案**

  Provide probe head, substrate(MLO/MLC/MLOC) and PCB one-stop service.

Fast Growing Applications

Future Trend for Probe Card

- ➢ Large size
- ➢ Hi pin count
- ➢ Hi CCC
- ➢ Hi speed
- ➢ Fine pitch
- ➢ Low force
- ➢ High/Low Temperature

Source: TSMC

HPC Challenges

High Force, High Power, and High Temperature are the challenges for HPC testing.

HPC testing challenges

- **Force**
- **Power**
- **Temperature**

Pin count

X1.5   X1.3   180KG

2017 2018 2019 2020 2021 2022

Power

X3.0   X1.5   1.5KW

2017 2018 2019 2020 2021 2022

Testing Condition

25C → 85C → 125C

3rd Annual SWTest Asia | Taiwan, Octorber 27-28, 2022

Source: TSMC

Interface Technical Complexity Check in

Complexity Trends are on pace to be at 2022 targets(1 Cycle) or in some cases beyond

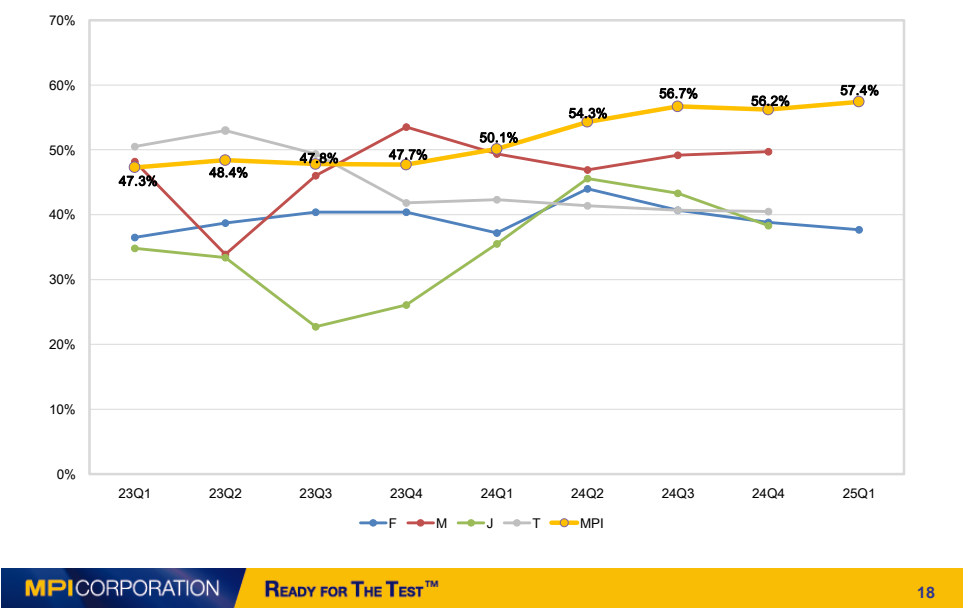"2x4 Scaling"=2xPins, 2xPerformance, every 4 years

SWTW SW Test Workshop
Semiconductor Wafer Test Workshop
2·0·1·8

Device Interface Challenges of the Next Decade

TERADYNE

Steve Ledford
Teradyne

June 3–6 2018

		2018	2022	2026
		Level 4	Level 5	Level 6
Pin Density	Pin Pitch	90um	70um	50um
	Total Contact Force	80kg	150kg	250kg
I/O Speed	Digital	32Gpbs	64Gpbs	128Gpbs
	RF/mmWave	< 12 GHz	29 GHz	+60 GHz
Device Power	Main Power	900 mV	750mV	625mV
	Single Rail	35A	50A	100A
	Impedance	2.2 mOhm	1.4 mOhm	0.8 mOhm
Thermal	Self Heating	75 W		
	Operating Range	0 to +80C	0 to +105C	-20 to +125C
Most Expensive Probe Card		$400K*	>$500K	>$700K

Source:Teradyne

CPC and VPC Yearly Status
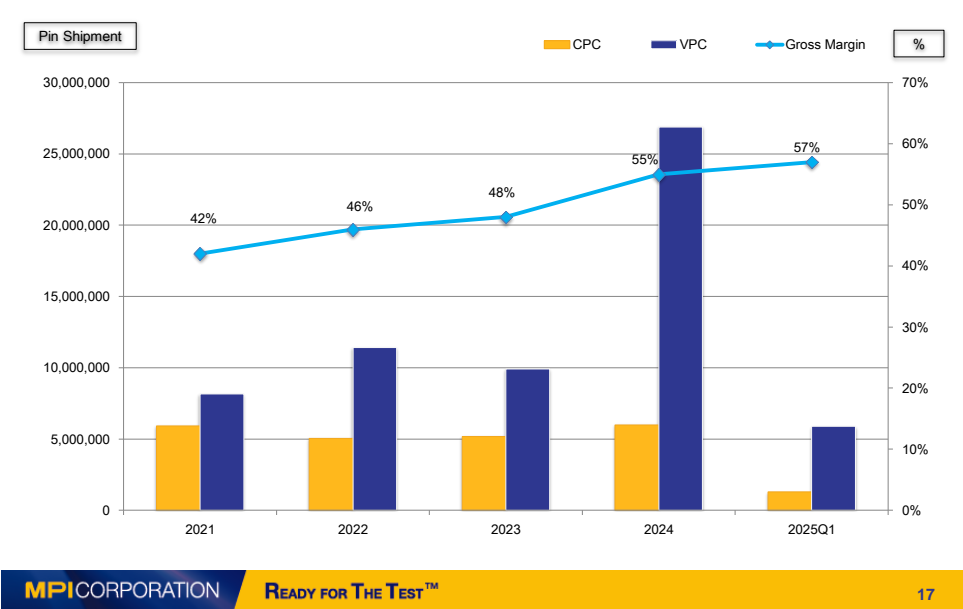
Gross Margin Between Global Peers

Operating Margin Between Global Peers
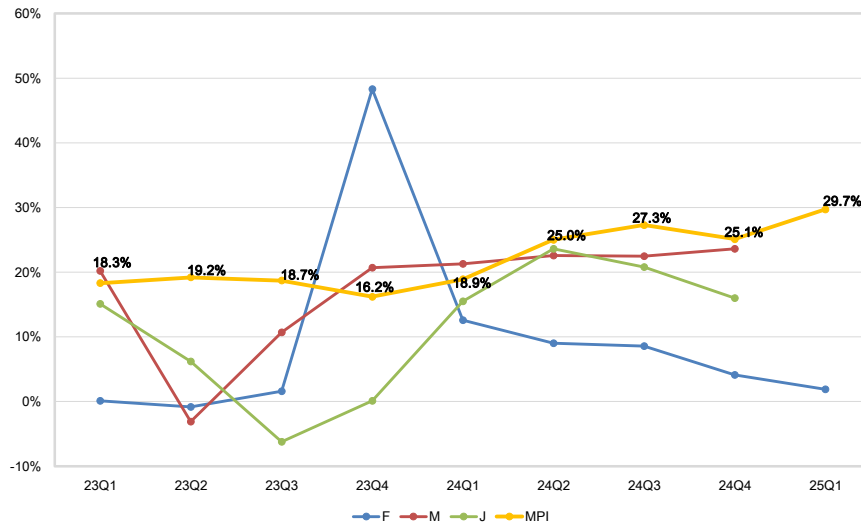
Photonics Automation

Product Portfolio and Capability

VEGA Line
Optical Sensing

AVIOR Line
Optical Communications

CAPELLA Line
LED/ Mini LED

GEMINI Line
Micro Display

➢ **High Power VCSEL Wafer Testing**
Wafer / Board Prober Development
Testing methodology Development

➢ **VCSEL / Photo-Detector Testing**
Wafer / Board Prober Development
Testing methodology Development

➢ **uLED Mass Production Methodology**
Wafer prober for large quantity die testing method

➢ **High Power VCSEL PKG Testing**
PKG Handler Development
Testing methodology Development

➢ **RF Character**
Wafer Level RF Testing Integration

➢ **Panel testing platform development**
Panel / Panel in-process testing platform

➢ **SiPh Die/PKG Platform**
SiPh Handler Development

Development Plan by Application

Optical Sensing	Optical Communications	Micro Display
➤ Focus on Sensing VCSEL Testing ➤ Production Wafer Prober in Low Temperature ➤ High Power Measurement Tool and Technology Development ➤ Flip Chip Wafer VCSEL testing Solution ➤ Package / Hybrid Device testing tool	➤ Focus on VCSEL/Photodetector Testing ➤ Wafer Prober for Dark / Responsivity / Capacity measurement ➤ RF Measurement Capability Development ➤ SiPh package testing approaching	➤ Lab and production wafer testing tool development ➤ Contacting Accuracy Improvement ➤ Innovative testing methodology ➤ Optical measurement in production methodology

PA: Work With Market Leaders

● **Value Enhanced Product Lines 客戶價值導向的產品線規劃**

MPI's experienced RD team comes across lighting and electrical fields with automation core technology that enables us to develop leading market solutions ie VCSEL & Micro LED.

● **Solid Global Clientele 穩固的全球客戶群**

MPI works closely with market leaders and international brand names for most advanced testing solutions.

● **Continuous Product Innovation 持續的產品創新**

Non stop RD investments helps MPI to provide high value added products that tackles clients' testing bottleneck.

Thermal: Customer Focus

- **Innovational Temperature System 創新的溫度測試系統**
Ongoing R&D investments in platforms and improvements leads MPI to meet customer demands. Thermal systems have a number of patents to provide efficient energy saving products that helps clients to fulfill ESG responsibility.

- **Top Skillful RD Team 頂尖優秀專業的研發團隊**

MPI's thermal solutions are developed by industry veterans with over 100 years of combined experience.

- **Deep Cooperation with Leading Customers for Engineering and Production demand**
與世界領導級大廠深度合作, 提供工程及量產需求

Product application expands to automotive , 5G/RF communication , fiber optic , and sensing fields.

AST: Unique Market Leader

● **Unique Global Position** 全球獨特的市場地位
Combining Analytical probing solution and RF measurement core
technology , MPI is top solution provider for full range hi-frequency
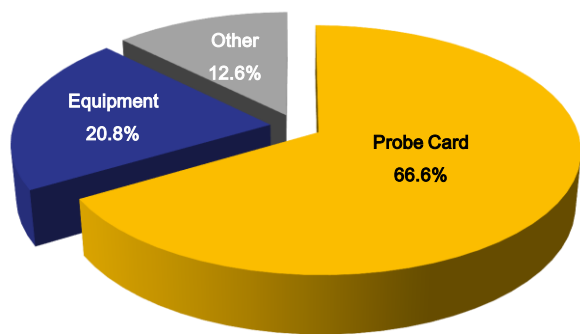response measurement.

● **VOC Design** 客戶導向設計

Design based on Voice of the customer to full-fill customers' needs.

● **Complete Solution** 提供完整的解決方案
Various series of products to cover wide range applications include
Device Modeling, RF & mmW, WLR, High-Power, Failure Analysis,
Extreme temperature test …etc.

MPICORPORATION

Financial Statements

READY FOR THE TEST™

2025 Q1 Shipment Breakdown

Other
12.6%

Equipment
20.8%

Probe Card
66.6%

Solid Performance

Revenue
NT$M

2021	2022	2023	2024	2025Q1
6,509	7,439	8,147	10,171	2,828

Gross Margin
NT$M

2021	2022	2023	2024	2025Q1
2,743	3,406	3,897	5,560	1,623

EPS

2021	2022	2023	2024	2025Q1
7.44	12.89	13.92	24.42	7.68

Continuous revenue growth driven by high customer satisfaction

Margin expansion is the result of strong RD investment

Accelerating profit earning shows MPI's shareholder commitment

ROE

30.00%

25.00%

20.00%

15.00%

10.00%

5.00%

0.00%

| 2019 | 2020 | 2021 | 2022 | 2023 | 2024 | 2025Q1 |

10.07% 14.24% 11.89% 18.73% 18.05% 27.17% 7.32%

Balance Sheet Highlight

NT$M	2025Q1		2024Q1	
Cash and Cash Equivalents	5,965	31%	2,546	20%
Fixed Assets	7,640	39%	5,669	45%
Total Assets	19,536	100%	12,565	100%
LT Debt	945	5%	1,453	12%
Shareholders' Equity	10,456	54%	8,206	65%
EBITDA	887	31%	482	23%

*EBITDA=operating income + depreciation & amortization expenses

P&L

NT$000	2025Q1		2024Q1	
Net Sales	2,828,698	100%	2,046,692	100%
Cost of Goods Sold	1,205,368	43%	1,020,800	50%
Gross Profit	1,623,330	57%	1,025,892	50%
Operating Expense	782,986	27%	639,117	32%
Operating Income	840,344	30%	386,775	18%
Investment Income & Others	47,380		95,592	
Net Income (after tax)	723,042	26%	392,927	19%
EPS (after tax)	7.68		4.18	